

- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 2A**

Electrical Characteristics

NO.	ITEM	SPECIFICATION
1	Center Frequency [fo]	5787.5MHz
2	Pass Band Width [BW]	5725~5850MHz
3	Insertion Loss	3.0dB max.
4	Ripple	1.0dB max.
5	Return Loss	10.0dB min.
6	Input/Output Impedance	50Ω
7	Max. Input Power	1W max.
8	Attenuation	31dB min. @ 5250~5350 MHz 12dB min. @ 5650 MHz 12dB min. @ 5925 MHz 40dB min. @ 6225 MHz
9	Operation Temperature Range	-40 to +105°C

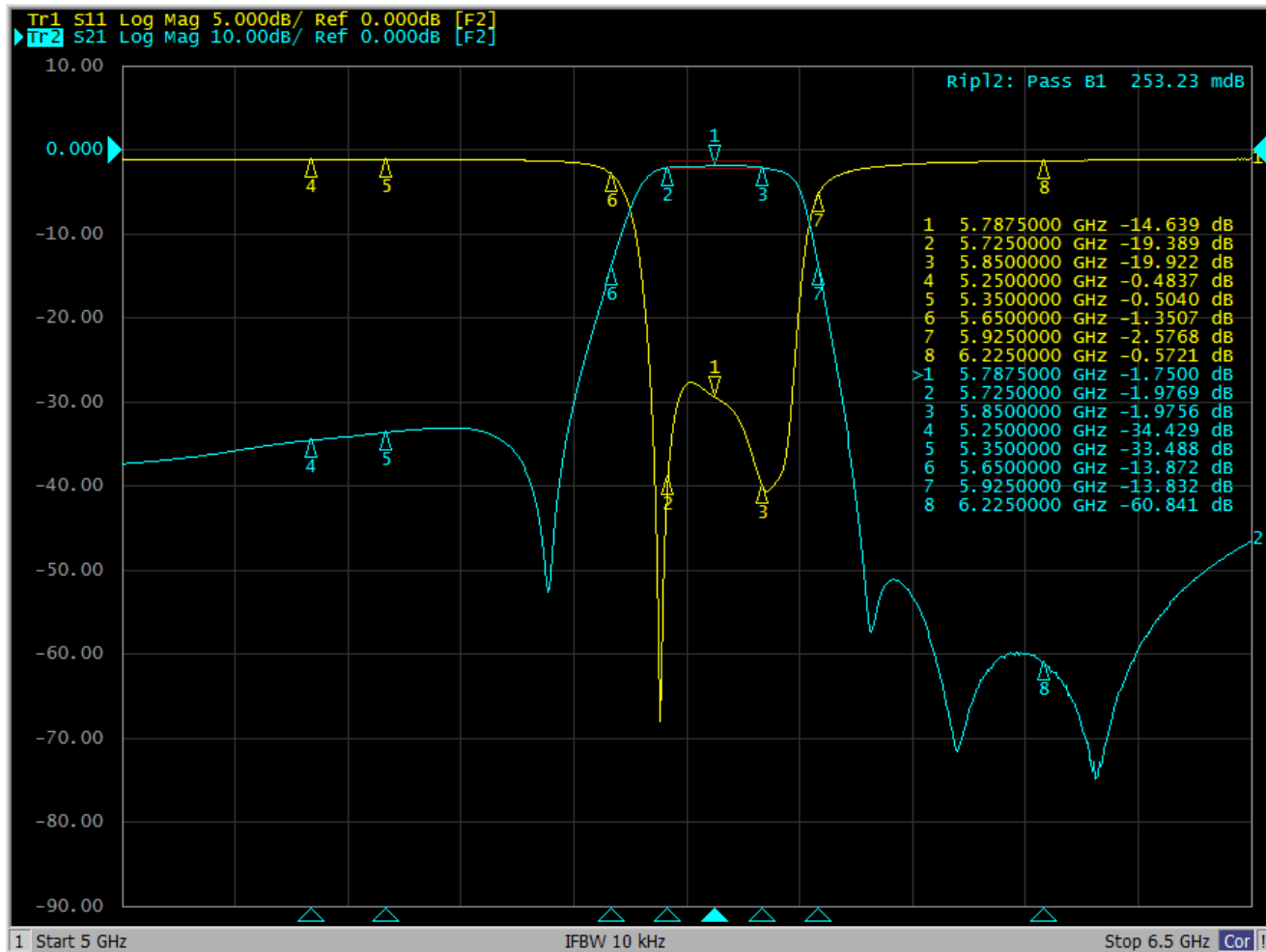


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

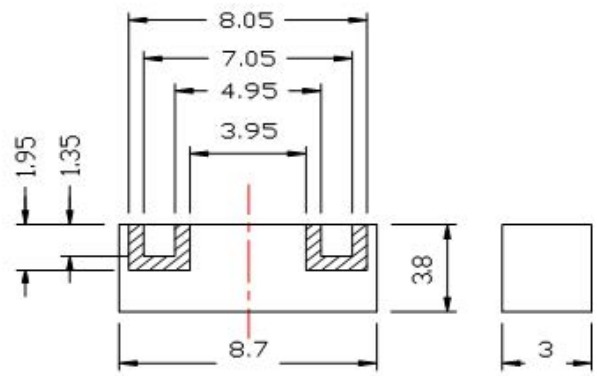
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. This component was always RoHS compliant from the first date of manufacture.

Data Result

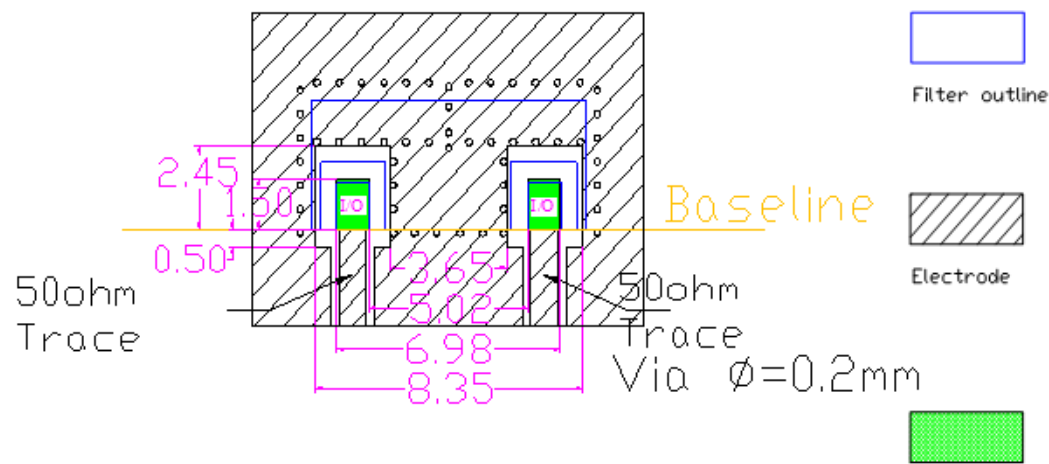


Dimension

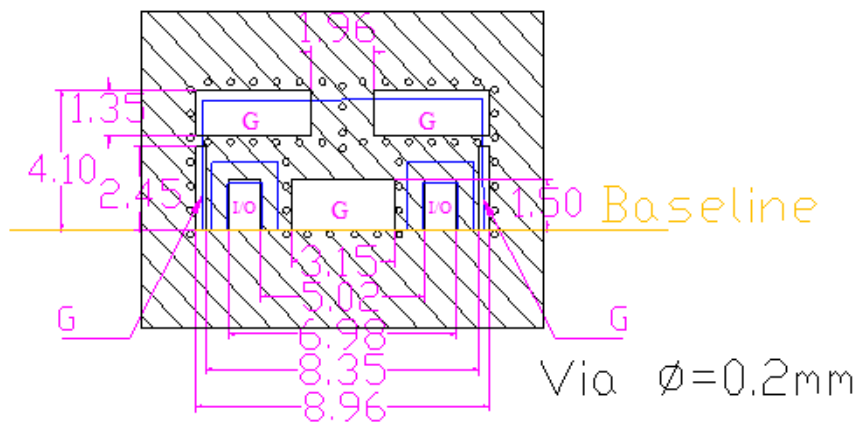


Dimensions in mm
Tolerance : ± 0.25

Footprint



Solder Resist Pattern



I/O pads must be connected to lines with 50 ohm impedance. In the application a termination of 50 ohm must be realized.



Solder Resist



Solder Land

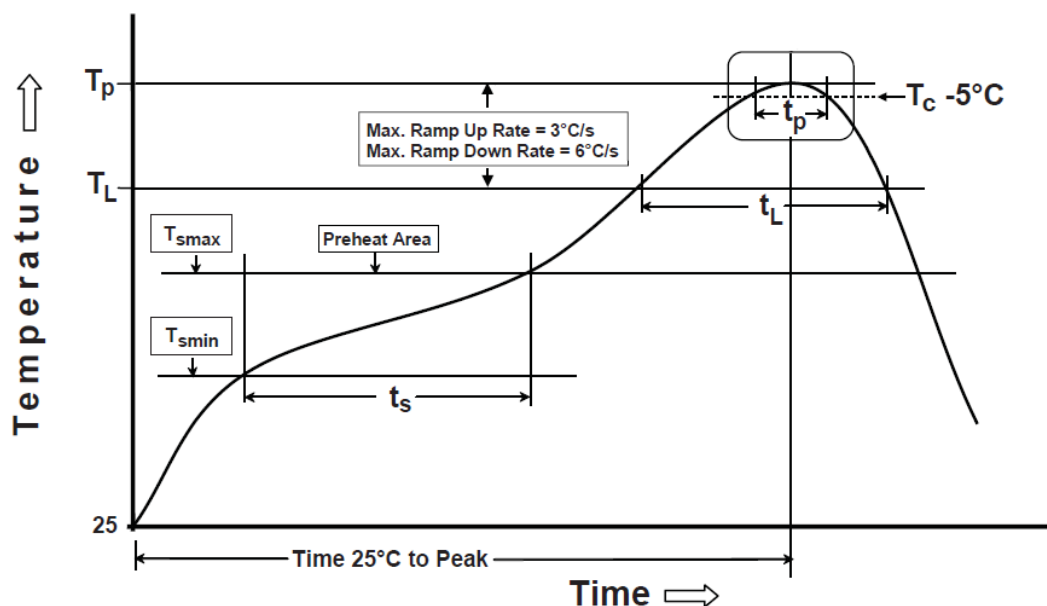
Recommended Reflow Soldering Profile

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150℃ 200℃ 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3℃/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217℃ 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260℃ 3 second
RAMP-DOWN	Rate	6℃ / second max.
Time from 25℃ to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note : All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

Recommended Reflow Soldering Profile

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

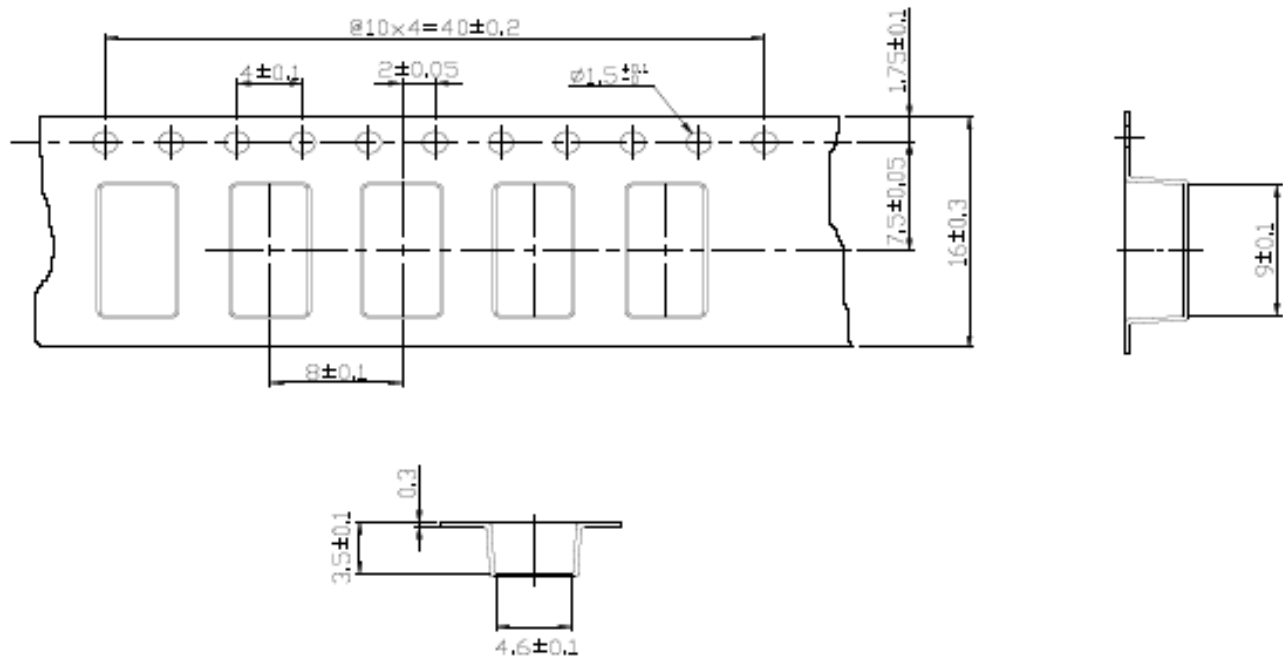
Soldering condition : Soldering iron temperature 270 ± 10 °C.

Apply preheating at 120℃ for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature 270 ± 10 °C or 3 seconds, it will make component surface peeling or damage. Soldering iron can not leakage of electricity.

Packing

Tape Dimension

Reel Count:
7" = 2000
13" = 10,000



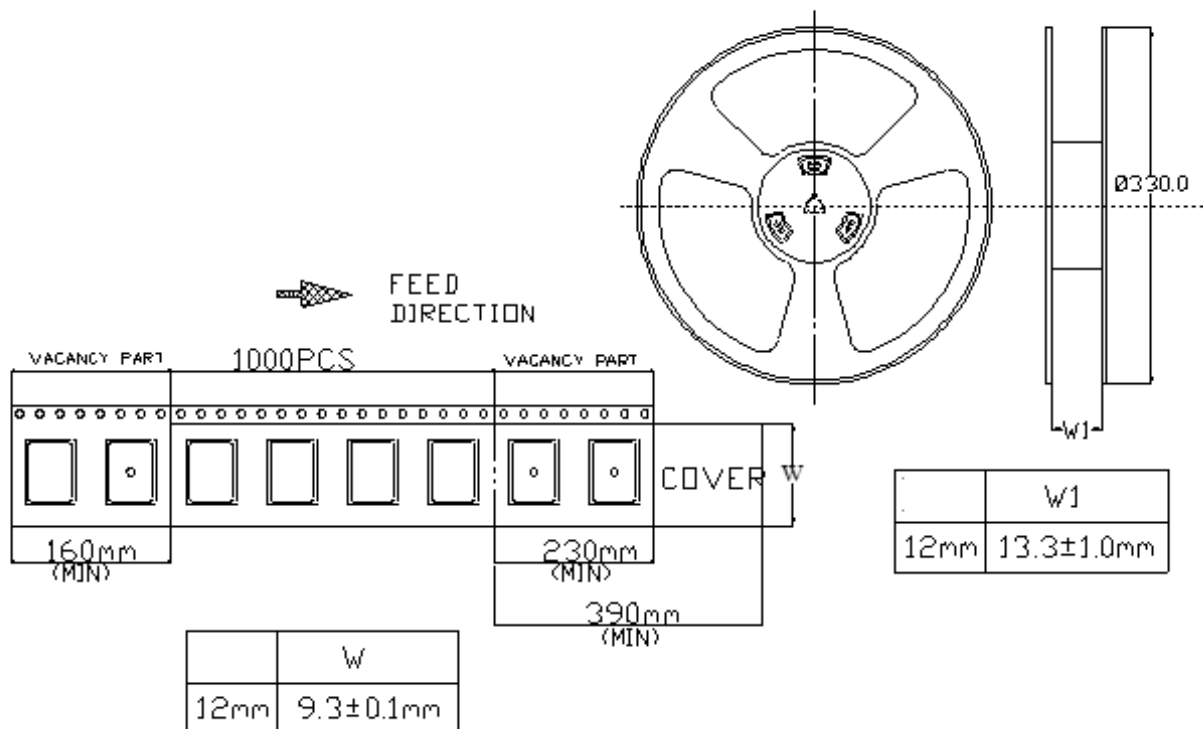
Reel Dimension

Reel Count:

7" = 2000

13" = 10,000

Tape and Reel Standard per ANSI/EIA-481



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C $\pm 5^\circ\text{C}$ peak (10 seconds).

